Signetics

SC87C51 CMOS Single-Chip 8-Bit EPROM Microcontroller

Product Specification

Microprocessor Division

DESCRIPTION

The Signetics SC87C51 is a high-performance microcontroller fabricated with Signetics high-density CMOS technology. The CMOS SC87C51 is functionally compatible with the NMOS SCN8031/SCN8051 and SC80C51 microcontrollers. The Signetics CMOS technology combines the high speed and density characteristics of HMOS with the low power attributes of CMOS. Signetics' epitaxial substrate minimizes latch-up sensitivity.

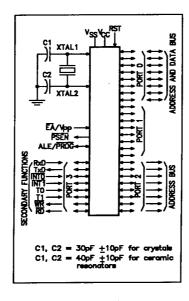
The SC87C51 contains a 4K x 8 EPROM, a 128 x 8 RAM, 32 I/O lines, two 16-bit counter/timers, a five-source, two priority level nested interrupt structure, a serial I/O port for either multiprocessor communications, I/O expansion or full duplex UART, and on-chip oscillator and clock circuits.

In addition, the SC87C51 has two software selectable modes of power reduction – idle mode and power-down mode. The idle mode freezes the CPU while allowing the RAM, timers, serial port, and interrupt system to continue functioning. The power-down mode saves the RAM contents but freezes the oscillator, causing all other chip functions to be inoperative.

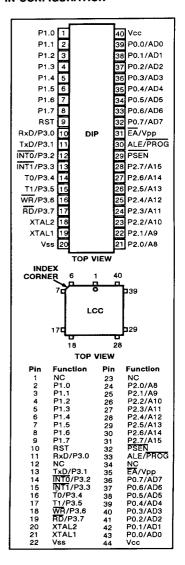
FEATURES

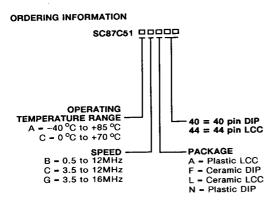
- SCN8031/SCN8051/SC80C51 compatible
 - 4K x 8 EPROM
 - 128 x 8 RAM
 - Two 16-bit counter/timers
 - Full duplex serial channel
 - Boolean processor
- Memory addressing capability
- 64K ROM and 64K RAM
 Power control modes:
- Idle mode
 - Power-down mode
- CMOS and TTL compatible
- Three speed ranges at Vcc = 5V ±10%
 - 3.5 to 12MHz
 - 3.5 to 16MHz
 - 0.5 to 12MHz
- Four package styles
- Extended temperature ranges
- OTP package available

LOGIC SYMBOL



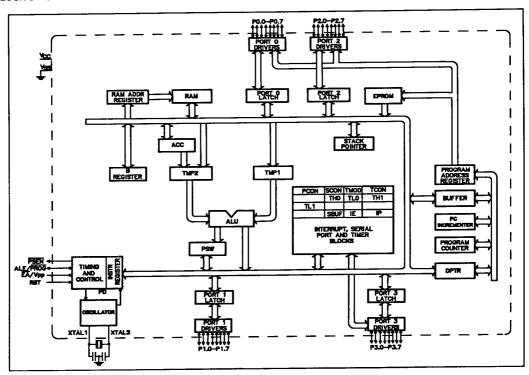
PIN CONFIGURATION





PART NUMBER SELECTION							
Part Number	Speed	Temperature and Package					
SC87C51CCF40	3.5 to 12MHz	0 to +70°C, ceramic DIP					
SC87C51CGF40	3.5 to 16MHz	0 to +70°C, ceramic DIP					
SC87C51CBF40	0.5 to 12MHz	0 to +70°C, ceramic DIP*					
SC87C51CCL44	3.5 to 12MHz	0 to +70°C, ceramic LCC					
SC87C51CGL44	3.5 to 16MHz	0 to +70°C, ceramic LCC					
SC87C51CBL44	0.5 to 12MHz	0 to +70°C, ceramic LCC*					
SC87C51CCN40	3.5 to 12MHz	0 to +70°C, plastic DIP					
SC87C51CGN40	3.5 to 16MHz	0 to +70°C, plastic DIP					
SC87C51CBN40	0.5 to 12MHz	0 to +70°C, plastic DIP*					
SC87C51CCA44	3.5 to 12MHz	0 to +70°C, plastic LCC					
SC87C51CGA44	3.5 to 16MHz	0 to +70°C, plastic LCC					
SC87C51CBA44	0.5 to 12MHz	0 to +70°C, plastic LCC*					
SC87C51ACN40	3.5 to 12MHz	-40 to +85°C, plastic DIP					
SC87C51AGN40	3.5 to 16MHz	-40 to +85°C, plastic DIP					
SC87C51ACA44	3.5 to 12MHz	-40 to +85°C, plastic LCC					
SC87C51AGA44	3.5 to 16MHz	-40 to +85°C, plastic LCC					
SC87C51ABN40	0.5 to 12MHz	-40 to +85°C, plastic DIP*					
SC87C51ABA44	0.5 to 12MHz	-40 to +85°C, plastic LCC*					
SC87C51ACF40	3.5 to 12MHz	-40 to +85°C, ceramic DIP					
SC87C51ACL44	3.5 to 12MHz	-40 to +85°C, ceramic LCC					
SC87C51ABL44	0.5 to 12MHz	-40 to +85°C, ceramic LCC*					
SC87C51AGL44	3.5 to 16MHz	-40 to +85°C, ceramic LCC					
SC87C51AGF40	3.5 to 16MHz	-40 to +85°C, ceramic DIP					
SC87C51ABF40	0.5 to 12MHz	-40 to +85°C, ceramic DIP°					
		*Contact Factory					

BLOCK DIAGRAM



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PIN DESCRIPTION

	PIN	NO.		MANE AND EUNOTION
MNEMONIC	DIP	LCC	TYPE	NAME AND FUNCTION
V _{SS}	20	22		Ground: 0V reference.
Vcc	40	44	i	Power Supply: This is the power supply voltage for normal, idle, and power-down operation.
P0.0-P0.7	39-32	43-36	1/0	Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pullups when emitting 1s. Port 0 also outputs the code bytes during program verification in the SC87C51. External pull-ups are required during program verification.
P1.0-P1.7	1-8	2-9	1/0	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I _{IL}). Port 1 also receives the low-order address byte during program memory verification.
P2.0-P2.7	21-28	24-31	1/0	Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pullups. (See DC Electrical Characteristics: I _{IL}). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 emits the contents of the P2 special function register.
P3.0-P3.7	10–17	11, 13–19	1/0	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pullups. Port 3 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I _{IL}). Port 3 also serves the special features of the SC80C51 family, as listed below:
	10 11 12 13 14 15 16 17	11 13 14 15 16 17 18 19	-000	RXD (P3.0): Serial input port TXD (P3.1): Serial output port INTO (P3.2): External interrupt INTO (P3.4): Timer 0 external input T1 (P3.5): Timer 1 external input WR (P3.6): External data memory write strobe RD (P3.7): External data memory read strobe
RST	9	10	1	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC} .
ALE/PROG	30	33	1/0	Address Latch Enable/Program Pulse: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and can be acused for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input (PROG) during EPROM programming.
PSEN	29	32		Program Store Enable: The read strobe to external program memory. When the SC87C51 is executing code from external program memory, PSEN is activated twice each machine cycle, except that two PSEN activations are skipped during each access to external data memory. PSEN is not activated during fetches from internal program memory.
EA/V _{PP}	31	35		External Access Enable/Programming Supply Voltage: EA must be externally held low to enable the device to fetch code from external program memory locations 0000H through 0FFFH. If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 0FFFH. This pin also receives the 12.75V programming supply voltage (V _{PP}) during EPROM programming.
XTAL1	19	21		Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	0	Crystal 2: Output from the inverting oscillator amplifier.

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator, as shown in the logic symbol, page 1.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

IDLE MODE

In the idle mode, the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed

in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

POWER-DOWN MODE

In the power-down mode, the oscillator is stopped and the instruction to invoke power-down is the last instruction executed. Only the contents of the on-chip RAM are preserved. A hardware reset is the only way to terminate the power-down mode. The control bits for the reduced power modes are in the special function register PCON.

DESIGN CONSIDERATIONS

At power-on, the voltage on VCC and RST must come up at the same time for a proper start-up.

When the idle mode is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write when idle is terminated by reset, the instruction following the one that invokes idle should not be one that writes to a port pin or to external memory.

Table 1 shows the state of I/O ports during low current operating modes.

Table 1. External Pin Status During Idle and Power-Down Modes

Mode	Program Memory	ALE	PSEN	Port 0	Port 1	Port 2	Port 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

Electrical Deviations from Commercial Specifications

for Extended Temperature Range D.C. and A.C. parameters not included here are the same as in the commercial temperature range table.

DC ELECTRICAL CHARACTERISTICS TA - -40°C to +85°C, VCC - 5V ±10%, VSS - 0V

Symbol V _{IL}		- · · · · · · · · · · · · · · ·	Lir	Unit	
	Parameter	Test Conditions	Min Max		
VII	Input low volatage (except EA)		-0.5	0.2V _{CC} -0.15	>
V _{IL1}	ĒĀ		0	0.2V _{CC} -0.35	٧
V _{IH}	Input high voltage (except XTAL1, RST)		0.2V _{CC} +1	V _{CC} +0.5	V
V _{IH1}	Input high voltage to XTAL1, RST		0.7V _{CC} +0.1	V _{CC} +0.5	V
IIL	Logical 0 input current (port 1, 2, 3)	V _{IN} = 0.45V		-75	μА
ITL	Logical 1 to 0 transition current (ports 1, 2, 3)	V _{IN} = 2.0V		-750	μА
Icc	Power supply current Active mode Idle mode Power down mode	V _{CC} = 4.5-5.5V, Frequency range = 3.5 to 12MHz		35 6 50	mA mA μA

SC87C51

ABSOLUTE MAXIMUM RATINGS 1, 2, 3

PARAMETER	RATING	UNIT
Operating temperature under bias	0 to +70 or -40 to +85	°C
Storage temperature range	-65 to +150	°C
Voltage on EA/V _{PP} pin to V _{SS}	0 to +13.0	V
Voltage on any other pin to V _{SS}	-0.5 to + 6.5	V
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.5	w

NOTES:

- Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.
- This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying voltages greater than the rated maxima Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to Vss unless otherwise
- noted.

DC ELECTRICAL CHARACTERISTICS TA = 0°C to +70°C or -40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V

Symbol	Parameter	Took Conditions		Limits			
Symbol	Parameter	Test Conditions	Min	Typical	Max	Unit	
VIL	Input low voltage, except EA ⁷		-0.5		0.2V _{CC} -0.1	٧	
V _{IL1}	Input low voltage to EA ⁷		0 .		0.2V _{CC} -0.3	٧	
V _{IH}	Input high voltage, except XTAL1, RST ⁷		0.2V _{CC} +.9		V _{CC} +0.5	٧	
V _{IH1}	Input high voltage, XTAL1, RST ⁷		0.7V _{CC}		V _{CC} +0.5	٧	
V _{OL}	Output low voltage, ports 1, 2, 3	I _{OL} = 1.6mA ²			0.45	٧	
V _{OL1}	Output low voltage, port 0, ALE, PSEN	I _{OL} = 3.2mA ²	1		0.45	٧	
V _{OH}	Output high voltage, ports 1, 2, 3, ALE, PSEN ³	t _{OH} = -60μΑ l _{OH} = -25μΑ l _{OH} = -10μΑ	2.4 0.75V _{CC} 0.9V _{CC}			V V	
V _{OH1}	Output high voltage (port 0 in external bus mode)	I _{OH} = -800μA I _{OH} = -300μA I _{OH} = -80μA	2.4 0.75V _{CC} 0.9V _{CC}			V V V	
I _I L	Logical 0 input current, ports 1, 2, 3 ⁷	V _{IN} - 0.45V			-50	μА	
ITL	Logical 1-to-0 transition current, ports 1, 2, 37	See note 4			-650	μА	
ILI	Input leakage current, port 0	V _{IN} = V _{IL} or V _{IH}			±10	μА	
lee	Power supply current: ⁷ Active mode @ 12MHz ⁵ Idle mode @ 12MHz ⁵ Power down mode	See note 6		11.5 1.3 3	25 4 50	mΑ mΑ μΑ	
R _{RST}	Internal reset pulldown resistor		50		300	kΩ	
C _{IO}	Pin capacitance				10	pF	

NOTES:

- Typical ratings are not guaranteed. The values listed are at room temperature, 5V.

 Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the Vols of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input.

 Capacitive loading on ports 0 and 2 may cause the VOH on ALE and PSEN to momentarily fall below the 0.9VCC specification when the
- address bits are stabilizing.
 Pins of ports 1, 2, and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its
- maximum value when VIN is approximately 2V.
- ICCMAX at other frequencies is given by:
 - Active mode: ICCMAX = 0.94 X FREQ + 13.71
 - Idle mode: ICCMAX = 0.14 X FREQ + 2.31
 - where FREQ is the external oscillator frequency in MHz. ICCMAX is given in mA. See Figure 8.
- See Figures 9 through 12 for ICC test conditions.
- These values apply only to $T_A = 0^{\circ}C$ to $+70^{\circ}C$. For $T_A = -40^{\circ}C$ to $+85^{\circ}C$, see table on page 4.

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AC ELECTRICAL CHARACTERISTICS TA - 0°C to +70°C or -40°C to +85°C, V_{CC} - 5V ±10%, V_{SS} - 0V¹, 2

			12MHz	CLOCK	VARIABLE CLOCK		
SYMBOL	FIGURE	PARAMETER	Min	Max	Min	Max	UNI
Program	Memory						
1/t _{CLCL}	1	Oscillator frequency: Speed Versions			0.5	12	М⊦
		SC87C51 B SC87C51 C			3.5	12	М⊦
		SC87C51 G	i		3.5	16	МН
t _{LHLL}	1	ALE pulse width	127		2t _{CLCL} -40		n:
tAVLL	1	Address valid to ALE low	28		t _{CLCL} -55		n
tLLAX	1	Address hold after ALE low	48		t _{CLCL} -35		n
tLLIV	1	ALE low to valid instruction in		234		4t _{CLCL} -100	_ n
tLLPL	1	ALE low to PSEN low	43		t _{CLCL} -40		n
tPLPH	1	PSEN pulse width	205	<u> </u>	3t _{CLCL} -45		l n
tPLIV	1	PSEN low to valid instruction in		145		3t _{CLCL} -105	n
t _{PXIX}	1	Input instruction hold after PSEN	0		0		<u> </u>
t _{PXIZ}	1	Input instruction float after PSEN		59		t _{CLCL} -25	n
tAVIV	1	Address to valid instruction in		312		5t _{CLCL} -105	n
†PLAZ	1 1	PSEN low to address float		10		10	r
Data Me					1		T
t _{RLRH}	2, 3	RD pulse width	400		6t _{CLCL} -100		r
twLwH	2, 3	WR pulse width	400		6t _{CLCL} -100		'
tRLDV	2, 3	RD low to valid data in		252		5t _{CLCL} -165	-
tRHDX	2, 3	Data hold after RD	0		0		r
tRHDZ	2, 3	Data float after RD		97		2t _{CLCL} -70	r
tLLDV	2, 3	ALE low to valid data in		517		8t _{CLCL} -150	<u> </u>
t _{AVDV}	2, 3	Address to valid data in		585		9t _{CLCL} -165	<u> </u>
tLLWL	2, 3	ALE low to RD or WR low	200	300	3t _{CLCL} -50	3t _{CLCL} +50	1
tavwL	2, 3	Address valid to WR low or RD low	203	<u> </u>	4t _{CLCL} -130		
tavwx	2, 3	Data valid to WR transition	23		t _{CLCL} -60		1
twhox	2, 3	Data hold after WR	33		t _{CLCL} -50		l r
RLAZ	2, 3	RD low to address float		0		0	1
twhilh	2, 3	RD or WR high to ALE high	43	123	t _{CLCL} -40	t _{CLCL} +40	1
External					1 00		т.
tCHCX	5	High time	20	ļ	20		-:
tCLCX	5	Low time	20	20	- 20	20	+-;
t _{CLCH}	5	Rise time Fall time		20		20	+ -
t _{CHCL} Shift Re	nieter	Fall time					
t _{XLXL}	4	Serial port clock cycle time	1.0		12t _{CLCL}		
tavxh	4	Output data setup to clock rising edge	700		10t _{CLCL} -133		-
txHQX	4	Output data hold after clock rising edge	50	ļ	2t _{CLCL} -117	ļ	₽.
txHDX	4	Input data hold after clock rising edge	0	700	0	104 100	<u> </u>
txHDV	4	Clock rising edge to input data valid		700		10t _{CLCL} -133	<u> </u>

NOTES:

Parameters are valid over operating temperature range unless otherwise specified.
 Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.

EXPLANATION OF THE AC SYMBOLS

Each timing symbol has five characters. The first character is always 't' (- time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

- A Address
- C Clock
- D Input data
- H Logic level high
- I Instruction (program memory contents)
- L Logic level low, or ALE

P- PSEN

Q - Output data

R - RD signal

V - Valid

W - WR signal

X - No longer a valid logic level Z - Float

Examples: tAVLL - Time for address valid to ALE low.

t_{LLPL} - Time for ALE low to PSEN low.

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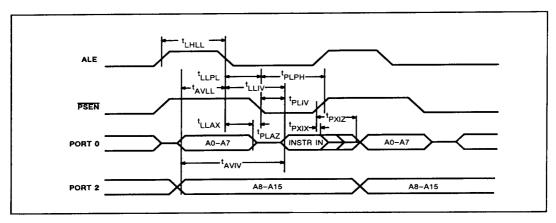


Figure 1. External Program Memory Read Cycle

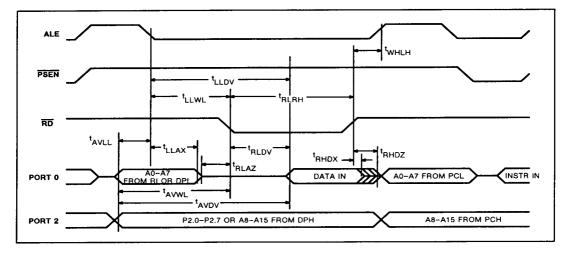


Figure 2. External Data Memory Read Cycle

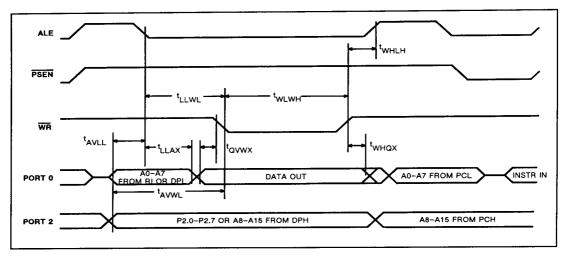


Figure 3. External Data Memory Write Cycle

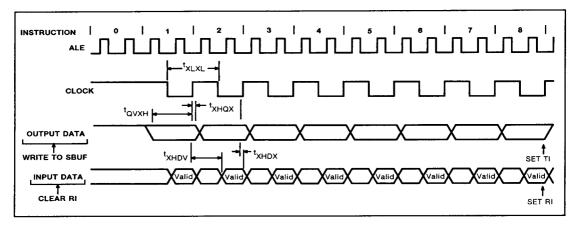


Figure 4. Shift Register Mode Timing

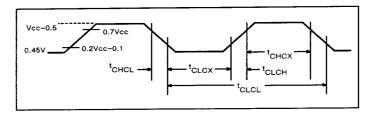


Figure 5. External Clock Drive

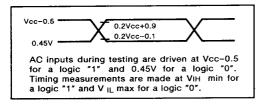


Figure 6. AC Testing Input/Output

V_{OH}-0.1V Timina Reference V_{OL}+0.1V Points

For timing purposes, a port is no longer floating when a 100mV change from load voltage occurs, and begins to float when a 100mV change from the loaded VOH/VOL level occurs. OH/IOL≥± 20mA.

EPROM CHARACTERISTICS

The SC87C51 is programmed by using a modified Quick-Pulse Programming™ algorithm. It differs from older methods in the value used for Vpp (programming supply voltage) and in the width and number of the ALE/PROG pulses.

The SC87C51 contains two signature bytes that can be read and used by an EPROM programming system to identify the device. The signature bytes identify the device as an SC87C51 manufactured by Signetics Corporation.

Table 2 shows the logic levels for reading the signature byte, and for programming the program memory, the encryption table, and the lock bits. The circuit configuration and waveforms for quick-pulse programming are shown in Figures 13 and 14. Figure 15 shows the circuit configuration for normal program memory verification.

QUICK-PULSE PROGRAMMING

The setup for microcontroller quick-pulse programming is shown in Figure 13. Note that the SC87C51 is running with a 4 to 6MHz oscillator. The reason the oscillator needs to be running is that the device is executing internal address and program data transfers.

The address of the EPROM location to be programmed is applied to ports 1 and 2, as shown in Figure 13. The code byte to be programmed into that location is

applied to port 0. RST, PSEN and pins of ports 2 and 3 specified in Table 2 are held at the "Program Code Data" levels indicated in Table 2. The ALE/PROG is pulsed low 25 times as shown in Figure

To program the encryption table, repeat the 25 pulse programming sequence for addresses 0 through 1FH, using the "Pgm Encryption Table" levels. Do not forget that after the encryption table is programmed, verification cycles will produce only encrypted data.

To program the lock bits, repeat the 25 pulse programming sequence using the "Pgm Lock Bit" levels. After one lock bit is programmed, further programming of the code memory and encryption table is disabled. However, the other lock bit can still be programmed.

Note that the EA/Vpp pin must not be allowed to go above the maximum specified Vpp level for any amount of time. Even a narrow glitch above that voltage can cause permanent damage to the device. The Vpp source should be well regulated and free of glitches and over-

Program Verification

If lock bit 2 has not been programmed, the on-chip program memory can be read out for program verification. The address of the program memory locations to be read is applied to ports 1 and 2 as

Figure 7. Float Waveform

shown in Figure 15. The other pins are held at the "Verify Code Data" levels indicated in Table 2. The contents of the address location will be emitted on port 0. External pull-ups are required on port 0 for this operation.

If the encryption table has been programmed, the data presented at port 0 will be the exclusive NOR of the gram byte with one of the encryption bytes. The user will have to know the encryption table contents in order to correctly decode the verification data. The encryption table itself cannot be read out.

Reading the Signature Bytes

The signature bytes are read by the same procedure as a normal verification of locations 030H and 031H, except that P3.6 and P3.7 need to be pulled to a logic low. The values are:

(030H) - 15H indicates manufactured by Signetics

(031H) - 92H indicates SC87C51

Program/Verify Algorithms

Any algorithm in agreement with the conditions listed in Table 2, and which satisfies the timing specifications, is suit-

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[™]Trademark phrase of Intel Corp.

Erasure Characteristics

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelengths shorter than approximately 4,000 angstroms. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room level fluorescent lighting) could cause inadvertent erasure. For this and secondary effects, it is recommended that an opaque label be placed over the window. For elevated temperature or solvent environments, use Kapton tape Fluorglas part number 2345-5 or equivalent.

The recommended erasure procedure is exposure to ultraviolet light (at 2537 angstroms) to an integrated dose of at least 15W-sec/cm². Exposing the EPROM to an ultraviolet lamp of 12,000μW/cm² rating for 20 to 39 minutes, at a distance of about 1 inch, should be sufficient.

Erasure leaves the array in an all 1s

Table 2. EPROM Programming Modes

MODE	RST	PSEN	ALE/PROG	EA/V _{PP}	P2.7	P2.6	P3.7	P3.6
Read signature	1	0	1	1	0	0	0	0
Program code data	1	0	0*	V _{PP}	1	0	1	1
Verify code data	1	0	1	1	0	0	1	1
Pgm encryption table	1	0	0*	V _{PP}	1	0	1	0
Pgm lock bit 1	1	0	0*	V _{PP}	1	1	1	1
Pgm lock bit 2	1	0	0*	V _{PP}	1	1	0	0

NOTES

^{*}ALE/PROG receives 25 programming pulses while V_{PP} is held at 12.75V. Each programming pulse is low for 100 µs (±10 µs) and high for a minimum of 10 µs.

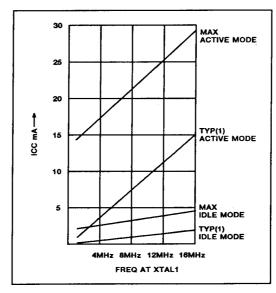


Figure 8. I_{CC} vs. FREQ Valid only within frequency specifications of the device under test

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^{1. &}quot;0" - valid low for that pin, "1" - valid high for that pin.

^{2.} $V_{PP} = 12.75V \pm 0.25V$.

^{3.} V_{CC} = 5V ±10% during programming and verification.

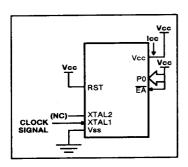


Figure 9. I_{CC} Test Condition, Active Mode All other pins are disconnected

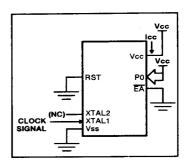


Figure 10. I_{CC} Test Condition, Idle Mode All other pins are disconnected

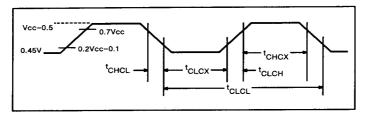


Figure 11. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes $t_{CLCH} = t_{CHCL} = 5 ns$

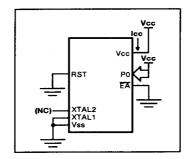


Figure 12. I_{CC} Test Conditions, Power Down Mode All other pins are disconnected. $V_{CC}=2V$ to 5.5V

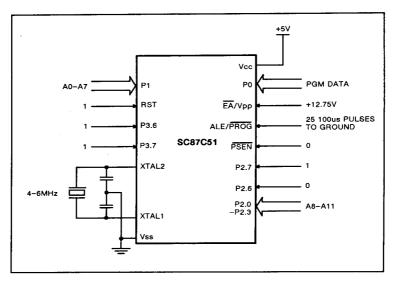


Figure 13. Programming Configuration

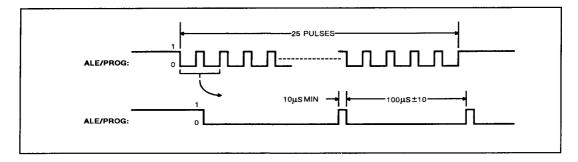


Figure 14. PROG Waveform

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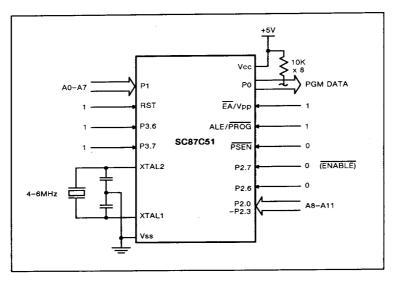


Figure 15. Program Verification

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS T_A - 21°C to +27°C, V_{CC} - 5V±10%, V_{SS} - 0V (see Figure 16)

SYMBOL	PARAMETER	MIN	MAX	UNIT
V _{PP}	Programming supply voltage	12.5	13.0	V
Ірр	Programming supply current		50	mA
1/t _{CLCL}	Oscillator frequency	4	6	MHz
tavgL	Address setup to PROG low	48t _{CLCL}		
†GHAX	Address hold after PROG	48t _{CLCL}		
t _{DVGL}	Data setup to PROG low	48t _{CLCL}		
tGHDX	Data hold after PROG	48t _{CLCL}		
t _{EHSH}	P2.7 (ENABLE) high to Vpp	48t _{CLCL}		
t _{SHGL}	V _{PP} setup to PROG low	10		μs
t _{GHSL}	V _{PP} hold after PROG	10		μs
t _{GLGH}	PROG width	90	110	μs
tavqv	Address to data valid		48t _{CLCL}	
†ELQV	ENABLE low to data valid		48t _{CLCL}	
t _{EHQZ}	Data float after ENABLE	0	48t _{CLCL}	
t _{GHGL}	PROG high to PROG low	10		μs

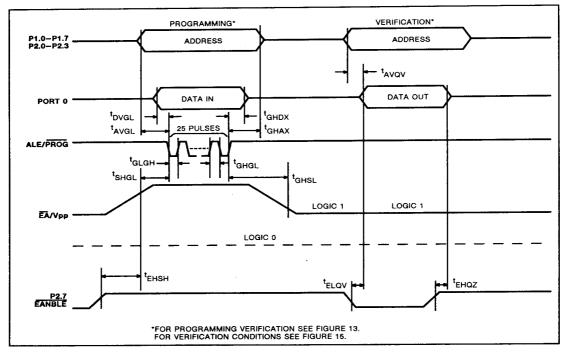


Figure 16. EPROM Programming and Verification